

# **Product Change Notification - GBNG-30UKAP366**

Date:

01 Feb 2020

**Product Category:** 

32-bit Microcontrollers

**Affected CPNs:** 



## **Notification subject:**

CCB 3802 Final Notice: Qualification of MTAI as an additional assembly site for selected Atmel products of the 58.85K wafer technology available in 48L TQFP (7x7x1 mm) package.

#### **Notification text:**

**PCN Status:** 

Final notification

**PCN Type:** 

Manufacturing Change

#### **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of MTAI as an additional assembly site for selected Atmel products of the 58.85K wafer technology available in 48L TQFP (7x7x1 mm) package.

### **Pre Change:**

Assembled at ANAP assembly site using 3230 die attach and C194 lead-frame material.

## **Post Change:**

Assembled at ANAP assembly site using 3230 die attach and C194 lead-frame material or assembled at MTAI assembly site using 3280 die attach and C7025 lead frame material.

Pre and Post Change Summary:

| The and host change cummary. |                   |                   |                      |  |  |  |  |  |  |  |
|------------------------------|-------------------|-------------------|----------------------|--|--|--|--|--|--|--|
|                              | Pre Change        | Post Change       |                      |  |  |  |  |  |  |  |
|                              |                   |                   | Microchip Technology |  |  |  |  |  |  |  |
| Assembly Site                | Amkor Technology  | Amkor Technology  | Thailand             |  |  |  |  |  |  |  |
|                              | Philippine (ANAP) | Philippine (ANAP) |                      |  |  |  |  |  |  |  |
|                              |                   |                   | (HQ) (MTAI)          |  |  |  |  |  |  |  |
| Wire material                | Au                | Au                | Au                   |  |  |  |  |  |  |  |
| Die attach material          | 3230              | 3230              | 3280                 |  |  |  |  |  |  |  |
| Molding compound             | G700              | G700              | G700                 |  |  |  |  |  |  |  |
| material                     | G700              | G700              | G700                 |  |  |  |  |  |  |  |
| Lead frame material          | C194              | C194              | C7025                |  |  |  |  |  |  |  |

#### Impacts to Data Sheet:

None

**Change Impact:** 

None

#### **Reason for Change:**

To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

#### **Change Implementation Status:**

In Progress

#### **Estimated First Ship Date:**

March 30, 2020 (date code: 2014)



NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

#### **Time Table Summary:**

|                                  | September 2019 |    |    |    | February 2020 |    |    | March 2020 |    |    |    |    |    |    |    |    |
|----------------------------------|----------------|----|----|----|---------------|----|----|------------|----|----|----|----|----|----|----|----|
| Workweek                         | 36             | 37 | 38 | 39 | 40            | -> | 05 | 06         | 07 | 80 | 09 | 10 | 11 | 12 | 13 | 14 |
| Initial PCN Issue Date           |                |    | Χ  |    |               |    |    |            |    |    |    |    |    |    |    |    |
| Qual Report<br>Availability      |                |    |    |    |               |    | Х  |            |    |    |    |    |    |    |    |    |
| Final PCN Issue Date             |                |    |    |    |               |    | Χ  |            |    |    |    |    |    |    |    |    |
| Estimated<br>Implementation Date |                |    |    |    |               |    |    |            |    |    |    |    |    |    |    | X  |

#### Method to Identify Change:

Traceability code

### **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

#### **Revision History:**

September 16, 2019: Issued initial notification.

**February 1, 2020:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on March 30, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachment(s):

PCN GBNG-30UKAP366 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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## Affected Catalog Part Numbers (CPN)

AT32UC3B1128-AUT

AT32UC3B1256-AUT

AT32UC3B164-AUT

AT32UC3B1128-AUR

AT32UC3B1256-AUR

AT32UC3B164-AUR

AT32UC3L0128-AUT

AT32UC3L0256-AUT

ATUC128L4U-AUT

ATUC256L4U-AUT

ATUC64L4U-AUT

AT32UC3L0128-AUR

AT32UC3L0256-AUR

ATUC128L4U-AUR

ATUC256L4U-AUR

ATUC64L4U-AUR

ATUC64D4-AUT

ATUC128D4-AUT

ATUC64D4-AUR

Date: Friday, January 31, 2020